

Product End-of-Life Disassembly Instructions

Product Category: **Networking**

Marketing Name / Model
[List multiple models if applicable.]

AP11-RW/APIN0303

AP11-US/APIN0303

AP11-RW-BDL/APIN0303

AP11-US-BDL/APIN0303

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	Plastic top cover and light pipe contain no brominated flame retardants.	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Top cover pad printing include ink and light pipe contains titanium dioxide pigment.	2
Components and waste containing asbestos		

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx screwdriver	T9
Static electric tweezers	NA
PH1 screwdriver	PH1
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- 1.
- 2.
- 3.
- 4.
- 5.
- 6.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

1. Use T9 screwdriver to remove the 4 screws on the chassis



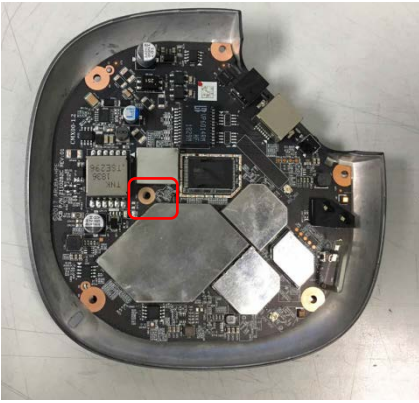
2. Open the top cover from the red arrow



3. Use tweezers to remove the antenna and then remove the top cover



4.Remove one screw from PCBA with PH1 screwdriver



4.Remove PCBA from cap

